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2012

Miller 2-1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application

Applicant(s): C.J. Miller et al.
Case: 2-1
Serial No.: 10/786,182
Filing Date: February 25, 2004
Group: 2812
Examiner: To Be Assigned

I hereby certify that this paper is being deposited on this date with the U.S. Postal Service as first class mail addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Signature:

Lisa A. Chulpi

Date: July 7, 2004

Title: Methods and Apparatus for Integrated Circuit Ball Bonding
with Substantially Perpendicular Wire Bond Profiles

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

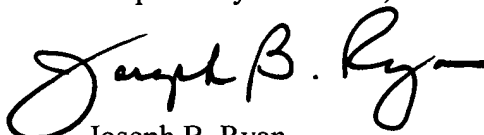
Sir:

Pursuant to 37 C.F.R. §§1.56, 1.97 and 1.98, Applicants' attorney wishes to bring to the attention of the Patent and Trademark Office the following document listed on the accompanying Form PTO-1449: V. Solberg, "Adapting Fine-Line Flex Circuits for 3D Multiple Die Packaging," Semiconductor Manufacturing, pp. 94-108, June 2003. A copy of the listed document is enclosed.

It is believed that there is no fee due in conjunction with the filing of this Information Disclosure Statement. In the event of non-payment or improper payment of a required fee, the Commissioner is authorized to charge or to credit **Ryan, Mason & Lewis, LLP Deposit Account No. 50-0762** as required to correct the error.

The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made, or as an admission that the information cited is considered to be material to patentability, or as a representation that no other material information exists.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Joseph B. Ryan". The signature is fluid and cursive, with a long horizontal stroke at the end.

Date: July 7, 2004

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FORM PTO-1449 (MODIFIED)

LIST OF PUBLICATIONS FOR
APPLICANT'S INFORMATION
DISCLOSURE STATEMENT



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U.S. PATENT DOCUMENTS

EXAMINER						FILING DATE
INITIAL	DOCUMENT NO.	DATE	NAME	CLASS/SUBCLASS	IF APPROPRIATE	

FOREIGN PATENT DOCUMENTS

EXAMINER						TRANSLATION
INITIAL	DOCUMENT NO.	DATE	COUNTRY	CLASS/SUBCLASS	YES	NO

OTHER DOCUMENTS

EXAMINER			
INITIAL	REF NO.	AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.	

1. V. Solberg, "Adapting Fine-Line Flex Circuits for 3D Multiple Die Packaging," Semiconductor Manufacturing, pp. 94-108, June 2003.

Examiner

Date Considered

Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.